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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Obsolete
Core Processor	CIP-51 8051
Core Size	8-Bit
Speed	72MHz
Connectivity	I <sup>2</sup> C, SMBus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	20
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1.25K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 3.6V
Data Converters	A/D 12x14b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	24-VFQFN Exposed Pad
Supplier Device Package	24-QFN (3x3)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/silicon-labs/efm8lb11f16es0-b-qfn24r">https://www.e-xfl.com/product-detail/silicon-labs/efm8lb11f16es0-b-qfn24r</a>

## 1. Feature List

The EFM8LB1 device family are fully integrated, mixed-signal system-on-a-chip MCUs. Highlighted features are listed below.

- Core:
  - Pipelined CIP-51 Core
  - Fully compatible with standard 8051 instruction set
  - 70% of instructions execute in 1-2 clock cycles
  - 72 MHz maximum operating frequency
- Memory:
  - Up to 64 kB flash memory (63 kB user-accessible), in-system re-programmable from firmware in 512-byte sectors
  - Up to 4352 bytes RAM (including 256 bytes standard 8051 RAM and 4096 bytes on-chip XRAM)
- Power:
  - Internal LDO regulator for CPU core voltage
  - Power-on reset circuit and brownout detectors
- I/O: Up to 29 total multifunction I/O pins:
  - Up to 25 pins 5 V tolerant under bias
  - Selectable state retention through reset events
  - Flexible peripheral crossbar for peripheral routing
  - 5 mA source, 12.5 mA sink allows direct drive of LEDs
- Clock Sources:
  - Internal 72 MHz oscillator with accuracy of  $\pm 2\%$
  - Internal 24.5 MHz oscillator with  $\pm 2\%$  accuracy
  - Internal 80 kHz low-frequency oscillator
  - External CMOS clock option
  - External crystal/RC oscillator (up to 25 MHz)
- Analog:
  - 14/12/10-Bit Analog-to-Digital Converter (ADC)
  - Internal calibrated temperature sensor ( $\pm 3\text{ }^{\circ}\text{C}$ )
  - 4 x 12-Bit Digital-to-Analog Converters (DAC)
  - 2 x Low-current analog comparators with adjustable reference
- Communications and Digital Peripherals:
  - 2 x UART, up to 3 Mbaud
  - SPI™ Master / Slave, up to 12 Mbps
  - SMBus™/I2C™ Master / Slave, up to 400 kbps
  - I2C High-Speed Slave, up to 3.4 Mbps
  - 16-bit CRC unit, supporting automatic CRC of flash at 256-byte boundaries
  - 4 Configurable Logic Units
- Timers/Counters and PWM:
  - 6-channel Programmable Counter Array (PCA) supporting PWM, capture/compare, and frequency output modes
  - 6 x 16-bit general-purpose timers
  - Independent watchdog timer, clocked from the low frequency oscillator
- On-Chip, Non-Intrusive Debugging
  - Full memory and register inspection
  - Four hardware breakpoints, single-stepping
- Pre-programmed UART or SMBus bootloader

With on-chip power-on reset, voltage supply monitor, watchdog timer, and clock oscillator, the EFM8LB1 devices are truly standalone system-on-a-chip solutions. The flash memory is reprogrammable in-circuit, providing nonvolatile data storage and allowing field upgrades of the firmware. The on-chip debugging interface (C2) allows non-intrusive (uses no on-chip resources), full speed, in-circuit debugging using the production MCU installed in the final application. This debug logic supports inspection and modification of memory and registers, setting breakpoints, single stepping, and run and halt commands. All analog and digital peripherals are fully functional while debugging. Device operation is specified from 2.2 V up to a 3.6 V supply. Devices are AEC-Q100 qualified (pending) and available in 4x4 mm 32-pin QFN, 3x3 mm 24-pin QFN, 32-pin QFP, or 24-pin QSOP packages. All package options are lead-free and RoHS compliant.

### 3.2 Power

All internal circuitry draws power from the VDD supply pin. External I/O pins are powered from the VIO supply voltage (or VDD on devices without a separate VIO connection), while most of the internal circuitry is supplied by an on-chip LDO regulator. Control over the device power can be achieved by enabling/disabling individual peripherals as needed. Each analog peripheral can be disabled when not in use and placed in low power mode. Digital peripherals, such as timers and serial buses, have their clocks gated off and draw little power when they are not in use.

**Table 3.1. Power Modes**

Power Mode	Details	Mode Entry	Wake-Up Sources
Normal	Core and all peripherals clocked and fully operational		
Idle	<ul style="list-style-type: none"> <li>Core halted</li> <li>All peripherals clocked and fully operational</li> <li>Code resumes execution on wake event</li> </ul>	Set IDLE bit in PCON0	Any interrupt
Suspend	<ul style="list-style-type: none"> <li>Core and peripheral clocks halted</li> <li>HFOSC0 and HFOSC1 oscillators stopped</li> <li>Regulator in normal bias mode for fast wake</li> <li>Timer 3 and 4 may clock from LFOSC0</li> <li>Code resumes execution on wake event</li> </ul>	<ol style="list-style-type: none"> <li>Switch SYSCLK to HFOSC0</li> <li>Set SUSPEND bit in PCON1</li> </ol>	<ul style="list-style-type: none"> <li>Timer 4 Event</li> <li>SPI0 Activity</li> <li>I2C0 Slave Activity</li> <li>Port Match Event</li> <li>Comparator 0 Falling Edge</li> <li>CLUn Interrupt-Enabled Event</li> </ul>
Stop	<ul style="list-style-type: none"> <li>All internal power nets shut down</li> <li>Pins retain state</li> <li>Exit on any reset source</li> </ul>	<ol style="list-style-type: none"> <li>Clear STOPCF bit in REG0CN</li> <li>Set STOP bit in PCON0</li> </ol>	Any reset source
Snooze	<ul style="list-style-type: none"> <li>Core and peripheral clocks halted</li> <li>HFOSC0 and HFOSC1 oscillators stopped</li> <li>Regulator in low bias current mode for energy savings</li> <li>Timer 3 and 4 may clock from LFOSC0</li> <li>Code resumes execution on wake event</li> </ul>	<ol style="list-style-type: none"> <li>Switch SYSCLK to HFOSC0</li> <li>Set SNOOZE bit in PCON1</li> </ol>	<ul style="list-style-type: none"> <li>Timer 4 Event</li> <li>SPI0 Activity</li> <li>I2C0 Slave Activity</li> <li>Port Match Event</li> <li>Comparator 0 Falling Edge</li> <li>CLUn Interrupt-Enabled Event</li> </ul>
Shutdown	<ul style="list-style-type: none"> <li>All internal power nets shut down</li> <li>Pins retain state</li> <li>Exit on pin or power-on reset</li> </ul>	<ol style="list-style-type: none"> <li>Set STOPCF bit in REG0CN</li> <li>Set STOP bit in PCON0</li> </ol>	<ul style="list-style-type: none"> <li>RSTb pin reset</li> <li>Power-on reset</li> </ul>

### 3.3 I/O

Digital and analog resources are externally available on the device's multi-purpose I/O pins. Port pins P0.0-P2.3 can be defined as general-purpose I/O (GPIO), assigned to one of the internal digital resources through the crossbar or dedicated channels, or assigned to an analog function. Port pins P2.4 to P3.7 can be used as GPIO. Additionally, the C2 Interface Data signal (C2D) is shared with P3.0 or P3.7, depending on the package option.

The port control block offers the following features:

- Up to 29 multi-functions I/O pins, supporting digital and analog functions.
- Flexible priority crossbar decoder for digital peripheral assignment.
- Two drive strength settings for each port.
- State retention feature allows pins to retain configuration through most reset sources.
- Two direct-pin interrupt sources with dedicated interrupt vectors (INT0 and INT1).
- Up to 24 direct-pin interrupt sources with shared interrupt vector (Port Match).

### 3.4 Clocking

The CPU core and peripheral subsystem may be clocked by both internal and external oscillator resources. By default, the system clock comes up running from the 24.5 MHz oscillator divided by 8.

The clock control system offers the following features:

- Provides clock to core and peripherals.
- 24.5 MHz internal oscillator (HFOSC0), accurate to  $\pm 2\%$  over supply and temperature corners.
- 72 MHz internal oscillator (HFOSC1), accurate to  $\pm 2\%$  over supply and temperature corners.
- 80 kHz low-frequency oscillator (LFOSC0).
- External RC, CMOS, and high-frequency crystal clock options (EXTCLK).
- Clock divider with eight settings for flexible clock scaling:
  - Divide the selected clock source by 1, 2, 4, 8, 16, 32, 64, or 128.
  - HFOSC0 and HFOSC1 include 1.5x pre-scalers for further flexibility.

### 3.5 Counters/Timers and PWM

#### Programmable Counter Array (PCA0)

The programmable counter array (PCA) provides multiple channels of enhanced timer and PWM functionality while requiring less CPU intervention than standard counter/timers. The PCA consists of a dedicated 16-bit counter/timer and one 16-bit capture/compare module for each channel. The counter/timer is driven by a programmable timebase that has flexible external and internal clocking options. Each capture/compare module may be configured to operate independently in one of five modes: Edge-Triggered Capture, Software Timer, High-Speed Output, Frequency Output, or Pulse-Width Modulated (PWM) Output. Each capture/compare module has its own associated I/O line (CEXn) which is routed through the crossbar to port I/O when enabled.

- 16-bit time base
- Programmable clock divisor and clock source selection
- Up to six independently-configurable channels
- 8, 9, 10, 11 and 16-bit PWM modes (center or edge-aligned operation)
- Output polarity control
- Frequency output mode
- Capture on rising, falling or any edge
- Compare function for arbitrary waveform generation
- Software timer (internal compare) mode
- Can accept hardware “kill” signal from comparator 0 or comparator 1

## Timers (Timer 0, Timer 1, Timer 2, Timer 3, Timer 4, and Timer 5)

Several counter/timers are included in the device: two are 16-bit counter/timers compatible with those found in the standard 8051, and the rest are 16-bit auto-reload timers for timing peripherals or for general purpose use. These timers can be used to measure time intervals, count external events and generate periodic interrupt requests. Timer 0 and Timer 1 are nearly identical and have four primary modes of operation. The other timers offer both 16-bit and split 8-bit timer functionality with auto-reload and capture capabilities.

Timer 0 and Timer 1 include the following features:

- Standard 8051 timers, supporting backwards-compatibility with firmware and hardware.
- Clock sources include SYSCLK, SYSCLK divided by 12, 4, or 48, the External Clock divided by 8, or an external pin.
- 8-bit auto-reload counter/timer mode
- 13-bit counter/timer mode
- 16-bit counter/timer mode
- Dual 8-bit counter/timer mode (Timer 0)

Timer 2, Timer 3, Timer 4, and Timer 5 are 16-bit timers including the following features:

- Clock sources for all timers include SYSCLK, SYSCLK divided by 12, or the External Clock divided by 8
- LFOSC0 divided by 8 may be used to clock Timer 3 and Timer 4 in active or suspend/snooze power modes
- Timer 4 is a low-power wake source, and can be chained together with Timer 3
- 16-bit auto-reload timer mode
- Dual 8-bit auto-reload timer mode
- External pin capture
- LFOSC0 capture
- Comparator 0 capture
- Configurable Logic output capture

## Watchdog Timer (WDT0)

The device includes a programmable watchdog timer (WDT) running off the low-frequency oscillator. A WDT overflow forces the MCU into the reset state. To prevent the reset, the WDT must be restarted by application software before overflow. If the system experiences a software or hardware malfunction preventing the software from restarting the WDT, the WDT overflows and causes a reset. Following a reset, the WDT is automatically enabled and running with the default maximum time interval. If needed, the WDT can be disabled by system software or locked on to prevent accidental disabling. Once locked, the WDT cannot be disabled until the next system reset. The state of the RST pin is unaffected by this reset.

The Watchdog Timer has the following features:

- Programmable timeout interval
- Runs from the low-frequency oscillator
- Lock-out feature to prevent any modification until a system reset

## 3.6 Communications and Other Digital Peripherals

### Universal Asynchronous Receiver/Transmitter (UART0)

UART0 is an asynchronous, full duplex serial port offering modes 1 and 3 of the standard 8051 UART. Enhanced baud rate support allows a wide range of clock sources to generate standard baud rates. Received data buffering allows UART0 to start reception of a second incoming data byte before software has finished reading the previous data byte.

The UART module provides the following features:

- Asynchronous transmissions and receptions.
- Baud rates up to  $\text{SYSCLK}/2$  (transmit) or  $\text{SYSCLK}/8$  (receive).
- 8- or 9-bit data.
- Automatic start and stop generation.
- Single-byte FIFO on transmit and receive.

## Universal Asynchronous Receiver/Transmitter (UART1)

UART1 is an asynchronous, full duplex serial port offering a variety of data formatting options. A dedicated baud rate generator with a 16-bit timer and selectable prescaler is included, which can generate a wide range of baud rates. A received data FIFO allows UART1 to receive multiple bytes before data is lost and an overflow occurs.

UART1 provides the following features:

- Asynchronous transmissions and receptions
- Dedicated baud rate generator supports baud rates up to  $\text{SYSCLK}/2$  (transmit) or  $\text{SYSCLK}/8$  (receive)
- 5, 6, 7, 8, or 9 bit data
- Automatic start and stop generation
- Automatic parity generation and checking
- Single-byte buffer on transmit and receive
- Auto-baud detection
- LIN break and sync field detection
- CTS / RTS hardware flow control

## Serial Peripheral Interface (SPI0)

The serial peripheral interface (SPI) module provides access to a flexible, full-duplex synchronous serial bus. The SPI can operate as a master or slave device in both 3-wire or 4-wire modes, and supports multiple masters and slaves on a single SPI bus. The slave-select (NSS) signal can be configured as an input to select the SPI in slave mode, or to disable master mode operation in a multi-master environment, avoiding contention on the SPI bus when more than one master attempts simultaneous data transfers. NSS can also be configured as a firmware-controlled chip-select output in master mode, or disabled to reduce the number of pins required. Additional general purpose port I/O pins can be used to select multiple slave devices in master mode.

- Supports 3- or 4-wire master or slave modes
- Supports external clock frequencies up to 12 Mbps in master or slave mode
- Support for all clock phase and polarity modes
- 8-bit programmable clock rate (master)
- Programmable receive timeout (slave)
- Two byte FIFO on transmit and receive
- Can operate in suspend or snooze modes and wake the CPU on reception of a byte
- Support for multiple masters on the same data lines

## System Management Bus / I2C (SMB0)

The SMBus I/O interface is a two-wire, bi-directional serial bus. The SMBus is compliant with the System Management Bus Specification, version 1.1, and compatible with the I<sup>2</sup>C serial bus.

The SMBus module includes the following features:

- Standard (up to 100 kbps) and Fast (400 kbps) transfer speeds
- Support for master, slave, and multi-master modes
- Hardware synchronization and arbitration for multi-master mode
- Clock low extending (clock stretching) to interface with faster masters
- Hardware support for 7-bit slave and general call address recognition
- Firmware support for 10-bit slave address decoding
- Ability to inhibit all slave states
- Programmable data setup/hold times
- Transmit and receive FIFOs (one byte) to help increase throughput in faster applications

### 3.10 Bootloader

All devices come pre-programmed with a UART0 bootloader or an SMBus bootloader. These bootloaders reside in the code security page, which is the last page of code flash; they can be erased if they are not needed.

The byte before the Lock Byte is the Bootloader Signature Byte. Setting this byte to a value of 0xA5 indicates the presence of the bootloader in the system. Any other value in this location indicates that the bootloader is not present in flash.

When a bootloader is present, the device will jump to the bootloader vector after any reset, allowing the bootloader to run. The bootloader then determines if the device should stay in bootload mode or jump to the reset vector located at 0x0000. When the bootloader is not present, the device will jump to the reset vector of 0x0000 after any reset.

More information about the bootloader protocol and usage can be found in *AN945: EFM8 Factory Bootloader User Guide*. Application notes can be found on the Silicon Labs website ([www.silabs.com/8bit-appnotes](http://www.silabs.com/8bit-appnotes)) or within Simplicity Studio by using the [Application Notes] tile.

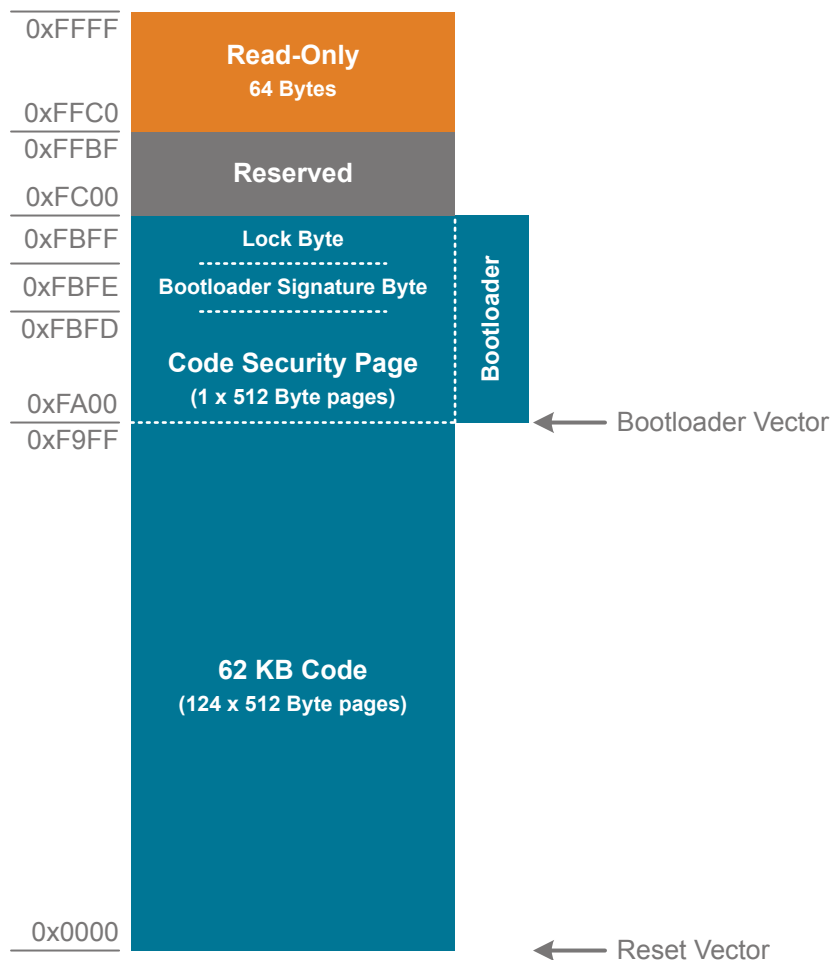


Figure 3.2. Flash Memory Map with Bootloader — 62.5 KB Devices

Table 3.2. Summary of Pins for Bootloader Communication

Bootloader	Pins for Bootload Communication
UART	TX – P0.4
	RX – P0.5
SMBus	P0.2 – SDA <sup>1</sup>
	P0.3 – SCL <sup>1</sup>

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Power Supply Rejection Ratio	PSRR <sub>ADC</sub>	At 1 kHz	—	66	—	dB
		At 1 MHz	—	43	—	dB
DC Performance						
Integral Nonlinearity	INL	14 Bit Mode	-3.5 <sup>4</sup>	-1.2 / +5	8.5 <sup>4</sup>	LSB
		12 Bit Mode	-1.9	-0.35 / +1	1.9	LSB
		10 Bit Mode	-0.6	±0.2	0.6	LSB
Differential Nonlinearity (Guaranteed Monotonic)	DNL	14 Bit Mode	-1 <sup>4</sup>	±1	2.5 <sup>4</sup>	LSB
		12 Bit Mode	-0.9	±0.3	0.9	LSB
		10 Bit Mode	-0.5	±0.2	0.5	LSB
Offset Error <sup>5</sup>	E <sub>OFF</sub>	14 Bit Mode	-8 <sup>4</sup>	-2.5	8 <sup>4</sup>	LSB
		12 Bit Mode	-2	0	2	LSB
		10 Bit Mode	-1	0	1	LSB
Offset Temperature Coefficient	TC <sub>OFF</sub>		—	0.011	—	LSB/°C
Slope Error	E <sub>M</sub>	14 Bit Mode	-15 <sup>4</sup>	—	15 <sup>4</sup>	LSB
		12 Bit Mode	-2.6	—	2.6	LSB
		10 Bit Mode	-1.1	—	1.1	LSB
Dynamic Performance 10 kHz Sine Wave Input 1 dB below full scale, Max throughput, using AGND pin						
Signal-to-Noise	SNR	14 Bit Mode	66 <sup>4</sup>	72	—	dB
		12 Bit Mode	64	68	—	dB
		10 Bit Mode	59	61	—	dB
Signal-to-Noise Plus Distortion	SNDR	14 Bit Mode	66 <sup>4</sup>	72	—	dB
		12 Bit Mode	64	68	—	dB
		10 Bit Mode	59	61	—	dB
Total Harmonic Distortion (Up to 5th Harmonic)	THD	14 Bit Mode	—	-74	—	dB
		12 Bit Mode	—	-72	—	dB
		10 Bit Mode	—	-69	—	dB
Spurious-Free Dynamic Range	SFDR	14 Bit Mode	—	74	—	dB
		12 Bit Mode	—	74	—	dB
		10 Bit Mode	—	71	—	dB

**Note:**

1. This time is equivalent to four periods of a clock running at 18 MHz + 2%.
2. Conversion Time does not include Tracking Time. Total Conversion Time is:  

$$\text{Total Conversion Time} = [\text{RPT} \times (\text{ADTK} + \text{NUMBITS} + 1) \times \text{T}(\text{SARCLK})] + (\text{T}(\text{ADCCLK}) \times 4)$$

where RPT is the number of conversions represented by the ADRPT field and ADCCLK is the clock selected for the ADC.
3. Absolute input pin voltage is limited by the V<sub>IO</sub> supply.
4. Measured with characterization data and not production tested.
5. The offset is determined using curve fitting since the specification is measured using linear search where the intercept is always positive.

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Negative Hysteresis Mode 3 (CPMD = 11)	HYS <sub>CP-</sub>	CPHYN = 00	—	-1.5	—	mV
		CPHYN = 01	—	-4	—	mV
		CPHYN = 10	—	-8	—	mV
		CPHYN = 11	—	-16	—	mV
Input Range (CP+ or CP-)	V <sub>IN</sub>		-0.25	—	V <sub>IO</sub> +0.25	V
Input Pin Capacitance	C <sub>CP</sub>		—	7.5	—	pF
Internal Reference DAC Resolution	N <sub>bits</sub>		6			bits
Common-Mode Rejection Ratio	CMRR <sub>CP</sub>		—	70	—	dB
Power Supply Rejection Ratio	PSRR <sub>CP</sub>		—	72	—	dB
Input Offset Voltage	V <sub>OFF</sub>	T <sub>A</sub> = 25 °C	-10	0	10	mV
Input Offset Tempco	TC <sub>OFF</sub>		—	3.5	—	μV/°

#### 4.1.14 Configurable Logic

**Table 4.14. Configurable Logic**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Propagation Delay	t <sub>DLY</sub>	Through single CLU Using an external pin	—	—	35.3	ns
		Through single CLU Using an internal connection	—	3	—	ns
Clocking Frequency	F <sub>CLK</sub>	1 or 2 CLUs Cascaded	—	—	73.5	MHz
		3 or 4 CLUs Cascaded	—	—	36.75	MHz

### 4.3 Absolute Maximum Ratings

Stresses above those listed in [Table 4.19 Absolute Maximum Ratings on page 30](#) may cause permanent damage to the device. This is a stress rating only and functional operation of the devices at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability. For more information on the available quality and reliability data, see the Quality and Reliability Monitor Report at <http://www.silabs.com/support/quality/pages/default.aspx>.

**Table 4.19. Absolute Maximum Ratings**

Parameter	Symbol	Test Condition	Min	Max	Unit
Ambient Temperature Under Bias	$T_{BIAS}$		-55	125	°C
Storage Temperature	$T_{STG}$		-65	150	°C
Voltage on VDD	$V_{DD}$		GND-0.3	4.2	V
Voltage on VIO <sup>2</sup>	$V_{IO}$		GND-0.3	$V_{DD}+0.3$	V
Voltage on I/O pins or RSTb, excluding P2.0-P2.3 (QFN24 and QSOP24) or P3.0-P3.3 (QFN32 and QFP32)	$V_{IN}$	$V_{IO} > 3.3\text{ V}$	GND-0.3	5.8	V
		$V_{IO} < 3.3\text{ V}$	GND-0.3	$V_{IO}+2.5$	V
Voltage on P2.0-P2.3 (QFN24 and QSOP24) or P3.0-P3.3 (QFN32 and QFP32)	$V_{IN}$		GND-0.3	$V_{DD}+0.3$	V
Total Current Sunk into Supply Pin	$I_{VDD}$		—	400	mA
Total Current Sourced out of Ground Pin	$I_{GND}$		400	—	mA
Current Sourced or Sunk by any I/O Pin or RSTb	$I_{IO}$		-100	100	mA
Operating Junction Temperature	$T_J$	$T_A = -40\text{ °C to }105\text{ °C}$	-40	130	°C

**Note:**

1. Exposure to maximum rating conditions for extended periods may affect device reliability.
2. In certain package configurations, the VIO and VDD supplies are bonded to the same pin.

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
15	P2.2	Multifunction I/O	Yes	P2MAT.2 CLU2OUT CLU1A.15 CLU2B.14 CLU3A.14	ADC0.15 CMP1P.4 CMP1N.4
16	P2.1	Multifunction I/O	Yes	P2MAT.1 I2C0_SCL CLU1B.14 CLU2A.15 CLU3B.15	ADC0.14 CMP1P.3 CMP1N.3
17	P2.0	Multifunction I/O	Yes	P2MAT.0 I2C0_SDA CLU1A.14 CLU2A.14 CLU3B.14	CMP1P.2 CMP1N.2
18	P1.7	Multifunction I/O	Yes	P1MAT.7 CLU0B.15 CLU1B.13 CLU2A.13	ADC0.13 CMP0P.9 CMP0N.9
19	P1.6	Multifunction I/O	Yes	P1MAT.6 CLU0A.15 CLU1B.12 CLU2A.12	ADC0.12
20	P1.5	Multifunction I/O	Yes	P1MAT.5 CLU0B.14 CLU1A.13 CLU2B.13	ADC0.11
21	P1.4	Multifunction I/O	Yes	P1MAT.4 CLU0A.14 CLU1A.12 CLU2B.12	ADC0.10
22	P1.3	Multifunction I/O	Yes	P1MAT.3 CLU0B.13 CLU1B.11 CLU2B.11 CLU3A.13	ADC0.9

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
23	P1.2	Multifunction I/O	Yes	P1MAT.2 CLU0A.13 CLU1A.11 CLU2B.10 CLU3A.12	ADC0.8 CMP0P.8 CMP0N.8
24	P1.1	Multifunction I/O	Yes	P1MAT.1 CLU0B.12 CLU1B.10 CLU2A.11 CLU3B.13	ADC0.7 CMP0P.7 CMP0N.7
25	P1.0	Multifunction I/O	Yes	P1MAT.0 CLU1OUT CLU0A.12 CLU1A.10 CLU2A.10 CLU3B.12	ADC0.6 CMP0P.6 CMP0N.6 CMP1P.1 CMP1N.1
26	P0.7	Multifunction I/O	Yes	P0MAT.7 INT0.7 INT1.7 CLU0B.11 CLU1B.9 CLU3A.11	ADC0.5 CMP0P.5 CMP0N.5 CMP1P.0 CMP1N.0
27	P0.6	Multifunction I/O	Yes	P0MAT.6 CNVSTR INT0.6 INT1.6 CLU0A.11 CLU1B.8 CLU3A.10	ADC0.4 CMP0P.4 CMP0N.4
28	P0.5	Multifunction I/O	Yes	P0MAT.5 INT0.5 INT1.5 UART0_RX CLU0B.10 CLU1A.9 CLU3B.11	ADC0.3 CMP0P.3 CMP0N.3

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
29	P0.4	Multifunction I/O	Yes	P0MAT.4 INT0.4 INT1.4 UART0_TX CLU0A.10 CLU1A.8 CLU3B.10	ADC0.2 CMP0P.2 CMP0N.2
30	P0.3	Multifunction I/O	Yes	P0MAT.3 EXTCLK INT0.3 INT1.3 CLU0B.9 CLU2B.9 CLU3A.9	XTAL2
31	P0.2	Multifunction I/O	Yes	P0MAT.2 INT0.2 INT1.2 CLU0OUT CLU0A.9 CLU2B.8 CLU3A.8	XTAL1 ADC0.1 CMP0P.1 CMP0N.1
32	P0.1	Multifunction I/O	Yes	P0MAT.1 INT0.1 INT1.1 CLU0B.8 CLU2A.9 CLU3B.9	ADC0.0 CMP0P.0 CMP0N.0 AGND
Center	GND	Ground			

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
6	P3.7 / C2D	Multifunction I/O / C2 Debug Data			
7	P3.3	Multifunction I/O			DAC3
8	P3.2	Multifunction I/O			DAC2
9	P3.1	Multifunction I/O			DAC1
10	P3.0	Multifunction I/O			DAC0
11	P2.6	Multifunction I/O			ADC0.19 CMP1P.8 CMP1N.8
12	P2.5	Multifunction I/O		CLU3OUT	ADC0.18 CMP1P.7 CMP1N.7
13	P2.4	Multifunction I/O			ADC0.17 CMP1P.6 CMP1N.6
14	P2.3	Multifunction I/O	Yes	P2MAT.3 CLU1B.15 CLU2B.15 CLU3A.15	ADC0.16 CMP1P.5 CMP1N.5
15	P2.2	Multifunction I/O	Yes	P2MAT.2 CLU2OUT CLU1A.15 CLU2B.14 CLU3A.14	ADC0.15 CMP1P.4 CMP1N.4
16	P2.1	Multifunction I/O	Yes	P2MAT.1 I2C0_SCL CLU1B.14 CLU2A.15 CLU3B.15	ADC0.14 CMP1P.3 CMP1N.3
17	P2.0	Multifunction I/O	Yes	P2MAT.0 I2C0_SDA CLU1A.14 CLU2A.14 CLU3B.14	CMP1P.2 CMP1N.2

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
18	P1.7	Multifunction I/O	Yes	P1MAT.7 CLU0B.15 CLU1B.13 CLU2A.13	ADC0.13 CMP0P.9 CMP0N.9
19	P1.6	Multifunction I/O	Yes	P1MAT.6 CLU0A.15 CLU1B.12 CLU2A.12	ADC0.12
20	P1.5	Multifunction I/O	Yes	P1MAT.5 CLU0B.14 CLU1A.13 CLU2B.13	ADC0.11
21	P1.4	Multifunction I/O	Yes	P1MAT.4 CLU0A.14 CLU1A.12 CLU2B.12	ADC0.10
22	P1.3	Multifunction I/O	Yes	P1MAT.3 CLU0B.13 CLU1B.11 CLU2B.11 CLU3A.13	ADC0.9
23	P1.2	Multifunction I/O	Yes	P1MAT.2 CLU0A.13 CLU1A.11 CLU2B.10 CLU3A.12	ADC0.8 CMP0P.8 CMP0N.8
24	P1.1	Multifunction I/O	Yes	P1MAT.1 CLU0B.12 CLU1B.10 CLU2A.11 CLU3B.13	ADC0.7 CMP0P.7 CMP0N.7

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
12	P1.5	Multifunction I/O	Yes	P1MAT.5 CLU2OUT CLU0B.14 CLU1A.13 CLU2B.13	ADC0.10 CMP1P.4 CMP1N.4
13	P1.4	Multifunction I/O	Yes	P1MAT.4 I2C0_SCL CLU0A.14 CLU1A.12 CLU2B.12	ADC0.9 CMP1P.3 CMP1N.3
14	P1.3	Multifunction I/O	Yes	P1MAT.3 I2C0_SDA CLU0B.13 CLU1B.11 CLU2B.11 CLU3A.13	CMP1P.2 CMP1N.2
15	GND	Ground			
16	P1.2	Multifunction I/O	Yes	P1MAT.2 CLU0A.13 CLU1A.11 CLU2B.10 CLU3A.12	ADC0.8
17	P1.1	Multifunction I/O	Yes	P1MAT.1 CLU0B.12 CLU1B.10 CLU2A.11 CLU3B.13	ADC0.7
18	P1.0	Multifunction I/O	Yes	P1MAT.0 CLU0A.12 CLU1A.10 CLU2A.10 CLU3B.12	ADC0.6

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
19	P0.7	Multifunction I/O	Yes	P0MAT.7 INT0.7 INT1.7 CLU1OUT CLU0B.11 CLU1B.9 CLU3A.11	ADC0.5 CMP0P.5 CMP0N.5 CMP1P.1 CMP1N.1
20	P0.6	Multifunction I/O	Yes	P0MAT.6 CNVSTR INT0.6 INT1.6 CLU0A.11 CLU1B.8 CLU3A.10	ADC0.4 CMP0P.4 CMP0N.4 CMP1P.0 CMP1N.0
21	P0.5	Multifunction I/O	Yes	P0MAT.5 INT0.5 INT1.5 UART0_RX CLU0B.10 CLU1A.9 CLU3B.11	ADC0.3 CMP0P.3 CMP0N.3
22	P0.4	Multifunction I/O	Yes	P0MAT.4 INT0.4 INT1.4 UART0_TX CLU0A.10 CLU1A.8 CLU3B.10	ADC0.2 CMP0P.2 CMP0N.2
23	P0.3	Multifunction I/O	Yes	P0MAT.3 EXTCLK INT0.3 INT1.3 CLU0B.9 CLU2B.9 CLU3A.9	XTAL2

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
24	P0.2	Multifunction I/O	Yes	P0MAT.2 INT0.2 INT1.2 CLU0OUT CLU0A.9 CLU2B.8 CLU3A.8	XTAL1 ADC0.1 CMP0P.1 CMP0N.1
Center	GND	Ground			

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
11	P2.1	Multifunction I/O	Yes	P2MAT.1 CLU1B.14 CLU2A.15 CLU3B.15	DAC1
12	P2.0	Multifunction I/O	Yes	P2MAT.0 CLU1A.14 CLU2A.14 CLU3B.14	DAC0
13	P1.7	Multifunction I/O	Yes	P1MAT.7 CLU0B.15 CLU1B.13 CLU2A.13	ADC0.12 CMP1P.6 CMP1N.6
14	P1.6	Multifunction I/O	Yes	P1MAT.6 CLU3OUT CLU0A.15 CLU1B.12 CLU2A.12	ADC0.11 CMP1P.5 CMP1N.5
15	P1.5	Multifunction I/O	Yes	P1MAT.5 CLU2OUT CLU0B.14 CLU1A.13 CLU2B.13	ADC0.10 CMP1P.4 CMP1N.4
16	P1.4	Multifunction I/O	Yes	P1MAT.4 I2C0_SCL CLU0A.14 CLU1A.12 CLU2B.12	ADC0.9 CMP1P.3 CMP1N.3
17	P1.3	Multifunction I/O	Yes	P1MAT.3 I2C0_SDA CLU0B.13 CLU1B.11 CLU2B.11 CLU3A.13	CMP1P.2 CMP1N.2

Dimension	Min	Typ	Max
<b>Note:</b> <ol style="list-style-type: none"> <li>All dimensions shown are in millimeters (mm) unless otherwise noted.</li> <li>Dimensioning and Tolerancing per ANSI Y14.5M-1994.</li> <li>This drawing conforms to JEDEC Solid State Outline MO-220.</li> <li>Recommended card reflow profile is per the JEDEC/IPC J-STD-020C specification for Small Body Components.</li> </ol>			

Dimension	Min	Typ	Max
aaa	0.20		
bbb	0.20		
ccc	0.10		
ddd	0.20		
theta	0°	3.5°	7°
<b>Note:</b> <ol style="list-style-type: none"> <li>1. All dimensions shown are in millimeters (mm) unless otherwise noted.</li> <li>2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.</li> <li>3. This drawing conforms to JEDEC outline MS-026.</li> <li>4. Recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.</li> </ol>			